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(71) Applicant: **FUJI ELECTRIC CO., LTD.**,
Kawasaki-shi (JP)

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(72) Inventors: **Norihiro KOMIYAMA**,
Matsumoto-city (JP); **Masahiro**
SASAKI, Azumino-city (JP)

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(73) Assignee: **FUJI ELECTRIC CO., LTD.**,
Kawasaki-shi (JP)

(57) **ABSTRACT**

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A semiconductor module, including: a first circuit board and a second circuit board respectively have a first switching element and a second switching element located thereon, each of the first and second switching elements having an emitter electrode; a first connecting portion and a second connecting portion respectively electrically connected to the emitter electrodes of the first and second switching elements over the first and second circuit boards; an auxiliary emitter terminal; and an auxiliary emitter wiring electrically connected to the auxiliary emitter terminal. The auxiliary emitter wiring includes: a branch point, a common wiring portion which connects the auxiliary emitter terminal and the branch point, and a first discrete wiring portion and a second discrete wiring portion which connect the branch point respectively to the first and second connecting portions, and which each have an inductance smaller than 10 percent of an inductance of the common wiring portion.

